

UF640

Power MOSFET

**18A, 200V, 0.18OHM,
N-CHANNEL POWER MOSFET**

■ DESCRIPTION

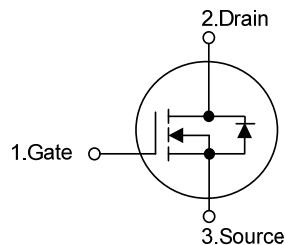
These kinds of n-channel power MOSFET field effect transistor have low conduction power loss, high input impedance, and high switching speed, Linear Transfer Characteristics, so can be use in a variety of power conversion applications.

The **UF640** suitable for resonant and PWM converter topologies.

■ FEATURES

- * $R_{DS(ON)} < 0.18\Omega$ @ $V_{GS} = 10V$, $I_D = 10A$
- * Ultra Low gate charge (typical 43nC)
- * Low reverse transfer capacitance (C_{RSS} = typical 100 pF)
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

■ SYMBOL



■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen-Free		1	2	3	
UF640L-TQ2-R	UF640G-TQ2-R	TO-263	G	D	S	Tape Reel
UF640L-TQ2-T	UF640G-TQ2-T	TO-263	G	D	S	Tube
UF640L-TN3-R	UF640G-TN3-R	TO-252	G	D	S	Tape Reel
UF640L-TN3-T	UF640G-TN3-T	TO-252	G	D	S	Tube
UF640L-TA3-T	UF640G-TA3-T	TO-220	G	D	S	Tube
UF640L-TF3-T	UF640G-TF3-T	TO-220F	G	D	S	Tube
UF640L-TF2-T	UF640G-TF2-T	TO-220F2	G	D	S	Tube
UF640L-AA3-R	UF640G-AA3-R	SOT-223	G	D	S	Tape Reel

UF640L-TA3-T	(1)Packing Type (2)Package Type (3)Lead Free	(1) T: Tube, R: Tape Reel (2) TA3: TO-220, TF3: TO-220F, TF2: TO-220F2, TN3: TO-252, TQ3: TO-263, AE3: SOT-223 (3) L: Lead Free, G: Halogen Free
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■ ABSOLUTE MAXIMUM RATING ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DSS}	200	V
Drain-Gate Voltage ($R_{GS}=20\text{k}\Omega$)	V_{DGR}	200	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current	I_D	18	A
Pulsed Drain Current (Note 2)	I_{DM}	72	A
Single Pulse Avalanche Energy Rating (Note 2)	E_{AS}	242	mJ
Maximum Power Dissipation	TO-220	123	W
	TO-220F	40	
	TO-220F2	42	
	TO-252	83	
	TO-263	139	
	SOT-223	66	
Junction Temperature	T_J	+150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

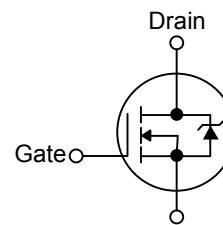
2. $L=3.37\text{mH}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, peak $I_{AS}=12\text{A}$, starting $T_J=25^\circ\text{C}$.

3. Pulse width limited by $T_{J(\text{MAX})}$

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/ TO-220F	62.5	$^\circ\text{C}/\text{W}$
	TO-220F2/ TO-263		
	TO-252		
	SOT-223		
Junction to Case	TO-220	1.01	$^\circ\text{C}/\text{W}$
	TO-220F	3.1	
	TO-220F2	2.9	
	TO-252	1.5	
	TO-263	0.9	
	SOT-223	1.8	

■ ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	200			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = \text{Rated } \text{BV}_{\text{DSS}}, V_{GS} = 0\text{V}$			25	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(\text{THR})}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2		4	V
Drain-Source On Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=10\text{A}$		0.14	0.18	Ω
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		805		pF
Output Capacitance	C_{OSS}			240		pF
Reverse Transfer Capacitance	C_{RSS}			46		pF
SWITCHING PARAMETERS						
Turn-ON Delay Time	$t_{D(\text{ON})}$	$V_{DD}=100\text{V}, I_D \approx 18\text{A}, R_G=9.1\Omega, R_L=5.4\Omega,$ MOSFET Switching Times are Essentially Independent of Operating Temperature		40	52	ns
Turn-ON Rise Time	t_R			58	72	ns
Turn-OFF Delay Time	$t_{D(\text{OFF})}$			127	152	ns
Turn-OFF Fall-Time	t_F			86	104	ns
Total Gate Charge	$Q_{G(\text{TOT})}$	$V_{GS}=10\text{V}, I_D \approx 18\text{A}, V_{DS}=0.8 \times \text{Rated } \text{BV}_{\text{DSS}}$ Gate Charge is Essentially Independent of Operating Temperature $I_{G(\text{REF})} = 1.5\text{mA}$		89	110	nC
Gate Source Charge	Q_{GS}			9		nC
Gate Drain Charge	Q_{GD}			24		nC
SOURCE TO DRAIN DIODE SPECIFICATIONS						
Diode Forward Voltage (Note)	V_{SD}	$T_J=25^\circ\text{C}, I_S=18\text{A}, V_{GS}=0\text{V},$			2.0	V
Continuous Source Current (body diode)	I_S	Integral Reverse p-n Junction Diode in the MOSFET 			18	A
Pulse Source Current (body diode) (Note)	I_{SM}				72	A
Reverse Recovery Time	t_{rr}	$T_J=25^\circ\text{C}, I_S=18\text{A}, dI_S/dt=100\text{A}/\mu\text{s}$	120	240	530	ns
Reverse Recovery Charge	Q_{RR}	$T_J=25^\circ\text{C}, I_S=18\text{A}, dI_S/dt=100\text{A}/\mu\text{s}$	1.3	2.8	5.6	μC

Note: Pulse Test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

■ TEST CIRCUIT

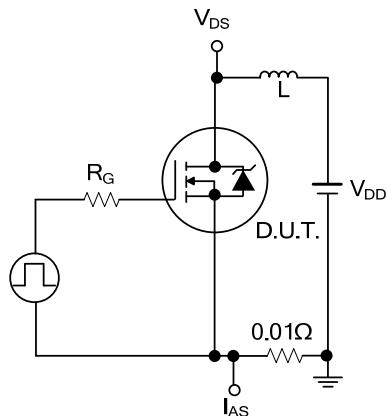


Fig. 1 Unclamped Energy Test Circuit

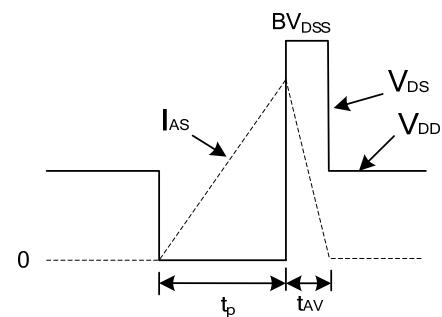


Fig. 2 Unclamped Energy Waveforms

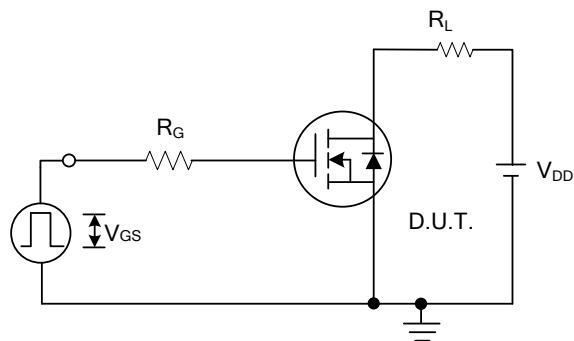


Fig. 3 Switching Time Test Circuit

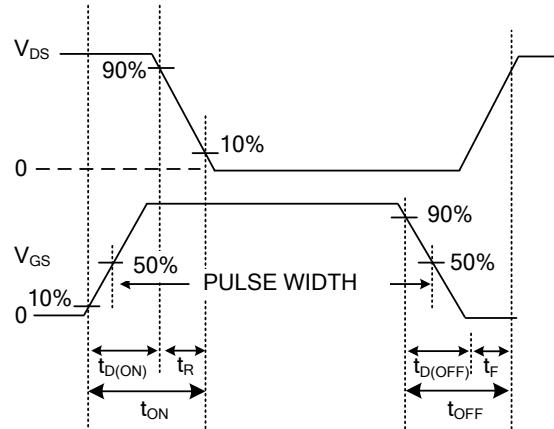


Fig. 4 Resistive Switching Waveforms

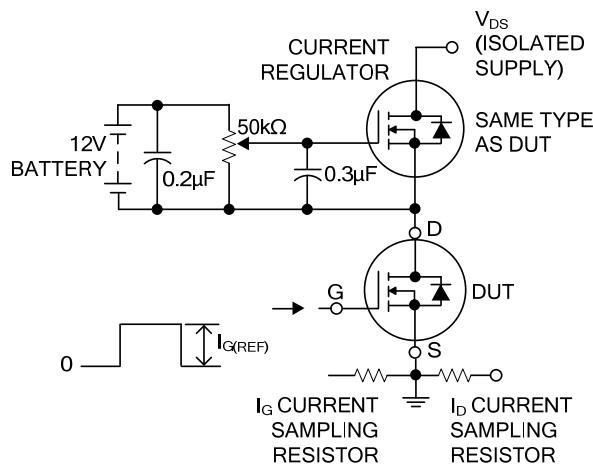


Fig. 5 Gate Charge Test Circuit

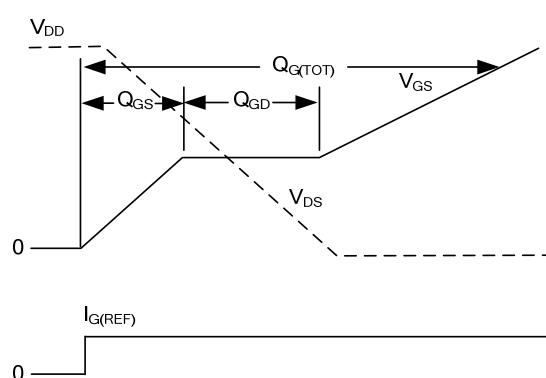
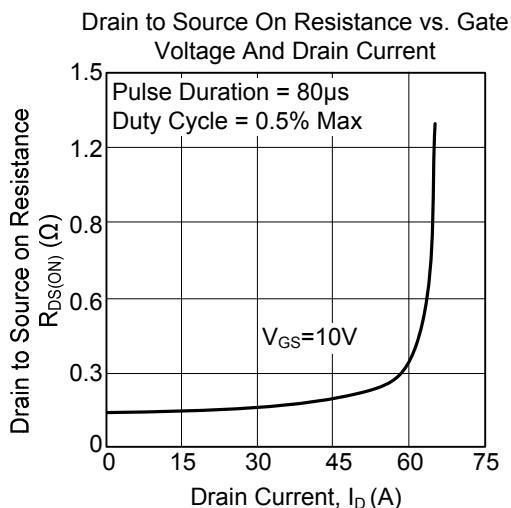
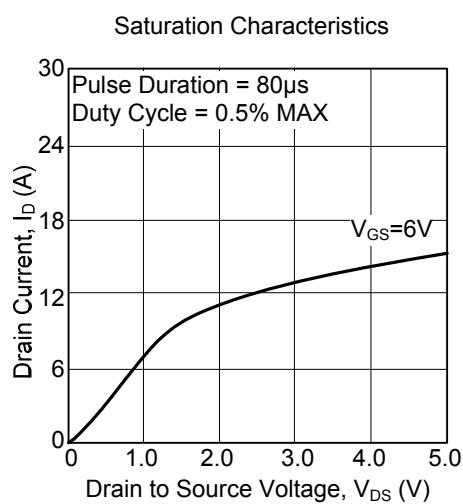


Fig. 6 Gate Charge Waveforms

■ TYPICAL CHARACTERISTICS



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